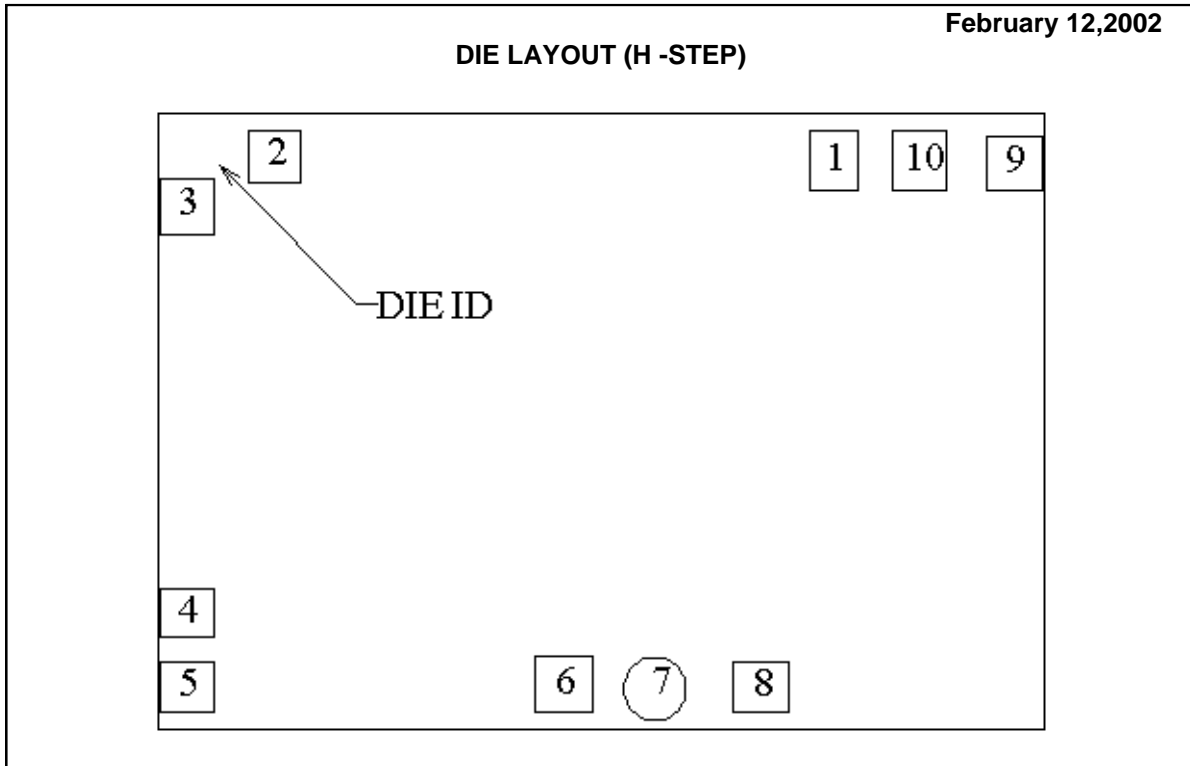


LM111 MD8 MW8
VOLTAGE COMPARATOR



DIE/WAFER CHARACTERISTICS

| Fabrication Attributes | | General Die Information | |
|-----------------------------|--|-----------------------------|--------------------------|
| Physical Die Identification | 111H | Bond Pad Opening Size (min) | 91 μ m x 112 μ m |
| Die Step | H | Bond Pad Metalization | ALUMINUM |
| Physical Attributes | | Passivation | VOM NITRIDE |
| Wafer Diameter | 150mm | Back Side Metal | Bare Back |
| Die Size (Drawn) | 1651 μ m x 1143 μ m 65mils x 45mils | Back Side Connection | Floating |
| Thickness | 330 μ m Nominal | | |
| Min Pitch | 140 μ m Nominal | | |

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

LM111 MD8 MW8
VOLTAGE COMPARATOR

| Die Bond Pad Coordinate Locations (H -Step) | | | | | | |
|--|--------|-----------------|------|----------|---|-----|
| (Referenced to die center, coordinates in μm) NC = No Connection | | | | | | |
| SIGNAL | PAD# | X/Y COORDINATES | | PAD SIZE | | |
| NAME | NUMBER | X | Y | X | Y | |
| GND | 1 | 434 | 485 | 91 | x | 112 |
| INPUT+ | 2 | -607 | 493 | 97 | x | 97 |
| INPUT- | 3 | -771 | 400 | 99 | x | 104 |
| V- | 4 | -771 | -356 | 99 | x | 91 |
| Balance | 5 | -771 | -495 | 99 | x | 91 |
| Balance/Strobe | 6 | -69 | -489 | 107 | x | 104 |
| NC | 7 | 114 | -483 | 117 | x | 117 |
| NC | 8 | 298 | -495 | 104 | x | 91 |
| Output | 9 | 768 | 479 | 104 | x | 99 |
| V+ | 10 | 593 | 485 | 99 | x | 112 |

LM111 MD8 MW8
VOLTAGE COMPARATOR

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IN U.S.A.

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Fax: 1 207 541 6140

IN EUROPE

Tel: 49 (0) 8141 351492 / 1495
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Tel: (852) 27371701

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